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[54] MATERIAL-SAVING RESIST SPINNER AND PROCESS

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Related U.S. Application Data

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[58] Field of Search **118/52, 50, 61, 64, 118/313, 315, 320; 134/902, 105**

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[57] ABSTRACT

Spin coating of resist on a semiconductor wafer is done in a controlled chamber, starting with introducing a resist solvent vapor into the chamber from a nozzle or an adjacent chamber, applying the resist by spraying a very thin layer of the resist material and then removing solvent from the chamber. The result is a saving in resist material and enhanced coating uniformity.

14 Claims, 3 Drawing Sheets

